

PATENT ASSIGNMENT COVER SHEET

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Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
YOUNGHO KIM	01/22/2015
MINSUN PARK	01/22/2015
HYUNGGON RYU	01/22/2015
JINWAN BAE	01/22/2015
RECEIVING PARTY DATA	
Name:	LG ELECTRONICS INC.
Street Address:	128, YEQUI-DAERO, YEONGDEUNGPO-GU
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	150-721
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29517879
CORRESPONDENCE DATA	
Fax Number:	(202)739-3001
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	202.739.3000
Email:	patents@morganlewis.com, ateckman@morganlewis.com
Correspondent Name:	COLLIN PARK
Address Line 1:	1111 PENNSYLVANIA AVE NW
Address Line 4:	WASHINGTON, D.C. 20004
ATTORNEY DOCKET NUMBER:	001082-7407
NAME OF SUBMITTER:	ROBERT J. GOODELL
SIGNATURE:	/Robert J. Goodell/
DATE SIGNED:	02/18/2015
Total Attachments: 2	
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ATTORNEY DOCKET NO.:
SOLE/JOINT INVENTION
(U.S. Rights Only)

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have, made an invention entitled:

MOBILE PHONE

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on ____, (Application No. ____); and


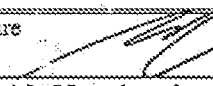
WHEREAS, LG ELECTRONICS INC., a corporation of Republic of Korea, whose post office address is 128, Yeoui-daero, Yeongdeungpo-gu, Seoul, 150-721, Republic of Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

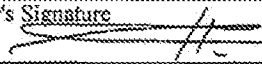
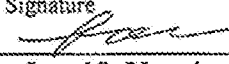
NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of First Assignor Youngho KIM	Assignor's Signature 	Date 2015. 1. 22
Address c/o Seocho R&D Campus, LG Electronics Inc. 19, Yangjae-daero 11gil, Seocho-gu, Seoul, Korea		Citizenship Republic of Korea
Full Name of Second Assignor Minsun PARK	Assignor's Signature 	Date 2015. 01. 22
Address c/o Seocho R&D Campus, LG Electronics Inc. 19, Yangjae-daero 11gil, Seocho-gu, Seoul, Korea		Citizenship Republic of Korea
Names of additional inventors attached <input checked="" type="checkbox"/> Yes <input type="checkbox"/> No		

Full Name of Third Assignor Hyunggon RYU	Assignor's Signature 	Date 2015.01.22
Address c/o Seocho R&D Campus, LG Electronics Inc. 19, Yangjae-daero 11gil, Seocho-gu, Seoul, Korea		Citizenship Republic of Korea
Full Name of Fourth Assignor Jinwan BAE	Assignor's Signature 	Date 2015.01.22
Address c/o Seocho R&D Campus, LG Electronics Inc. 19, Yangjae-daero 11gil, Seocho-gu, Seoul, Korea		Citizenship Republic of Korea
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		